



# Product Change Notification

**Change Notification #:** 118829-00  
**Change Title:** 2U Hot-swap 8x2.5 inch Dual Port Upgrade Drive Bay Kit A2U8X25S3DPDK2, Single, PCN 118829-00, Product Design, Product Material  
HSPB FW update, adding cable and gasket, alternative component  
**Date of Publication:** January 6, 2022

## Key Characteristics of the Change:

Product Design, Product Material

## Forecasted Key Milestones:

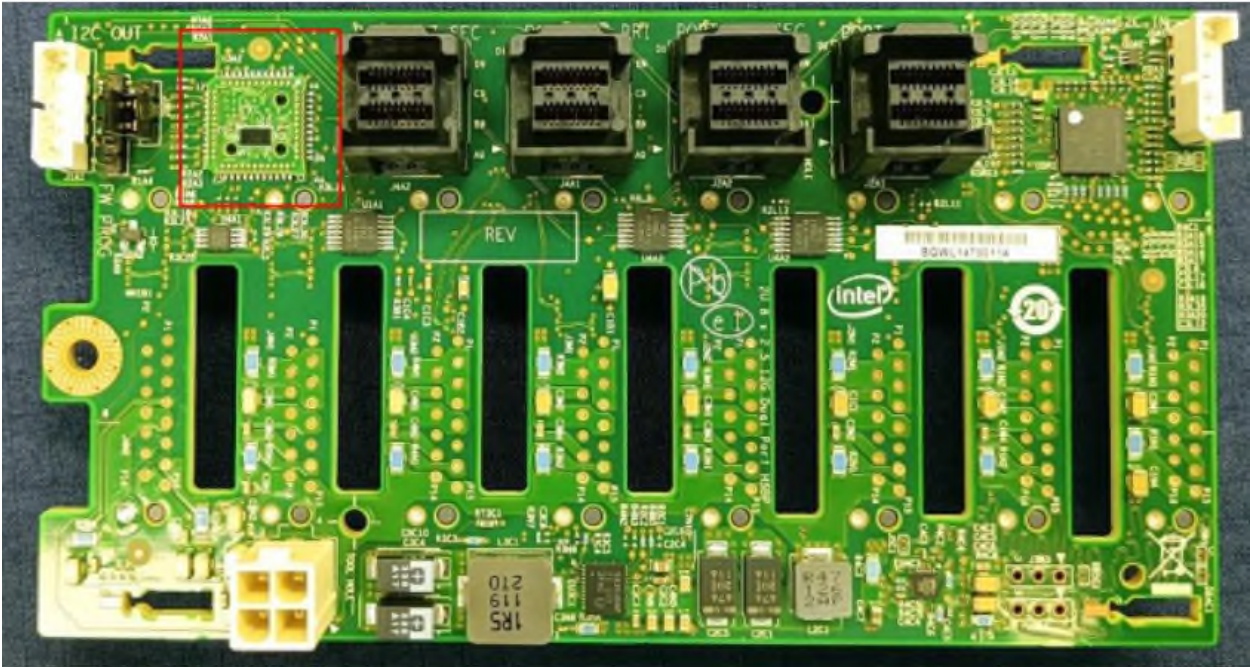
<b>Date Customer Must be Ready to Receive Post-Conversion Material*</b>	February 04, 2022
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

Intel is implementing the following changes on the systems and accessories listed in the "Products Affected" table below:

1. Updating the Hot-Swap Back Plane (HSBP) firmware from version 1.40 to 1.41 to enhance LEDs responses.
2. Adding I2C communication cable J20956-001.
3. A gasket has been added on each side of the 2.5" tool less carrier (TLC), improving the flow of electricity.
4. Due to Integrated Circuit (IC) shortage from the supplier, a Programmable System-On-Chip (PSOC) used on the Hot Swap Backplanes needs to be replaced with an alternative component. The new component is identical in function than previous one but differs in form factor. For business continuity, demand fulfillment and to minimize customer impact, an interposer PCB supporting the new component was used. The new component has passed all functional and electrical validation test successfully.



**Customer Impact of Change and Recommended Action:**

Intel anticipates no impact to customers.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes

### Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
2U Hot-swap 8x2.5 inch Dual Port Upgrade Drive Bay Kit A2U8X25S3DPDK2, Single	A2U8X25S3DPDK2	958247	J56723-002	G97166-272	J56723-004	G97166-274

### PCN Revision History:

**Date of Revision:**

January 6, 2022

**Revision Number:**

00

**Reason:**

Originally Published PCN



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## 118829-00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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